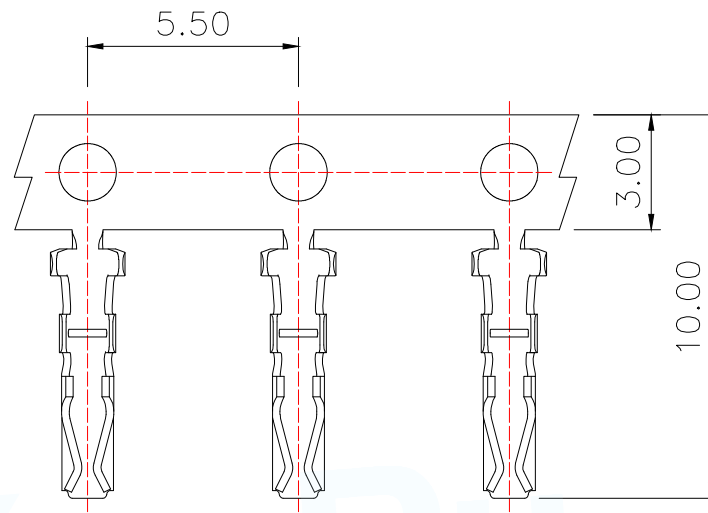
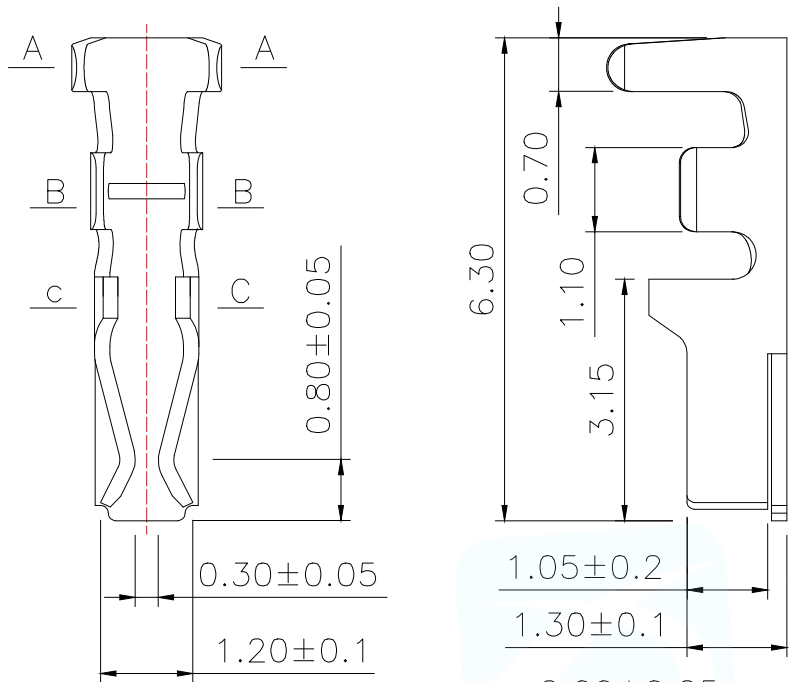
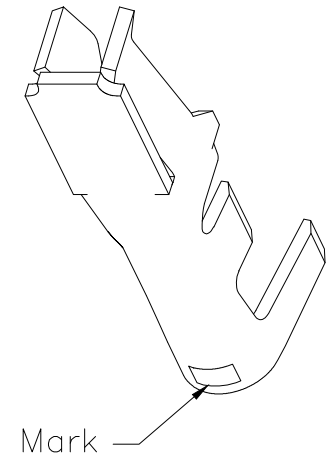
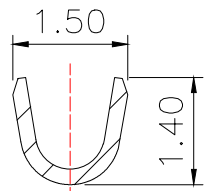




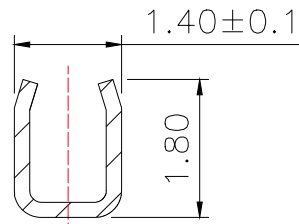
料带图 比率: 1:2



SECTION A-A



SECTION B-B



SECTION C-C

Specification:

1. Material: Phos.Bronze Tin-Plated

Coating: Sn>80u",

2. Applicable wire: AWG#30-#24

4. The appearance of the parts shall not have harmful burrs, sharp corners, sharp edges and mechanical damage: the surface plating should be uniform and bright, without fog spots, peeling and other defects;

MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co., Ltd	
		TITLE: 2.0 Pitch	
		PAR	WAFER-HY2.0-DZ
		DWN	
		CHKD	
DECIMALS:	ANGLES:	APVD	
X.X $\pm$ 0.30	X.* $\pm$ 5°	SCALE:A	UNIT:MM
X.XX $\pm$ 0.25	X.X° $\pm$ 1°	SIZE:A4	SHEET:1F1
X.XXX $\pm$ 0.15		CUSTOMER COPY	REV:A